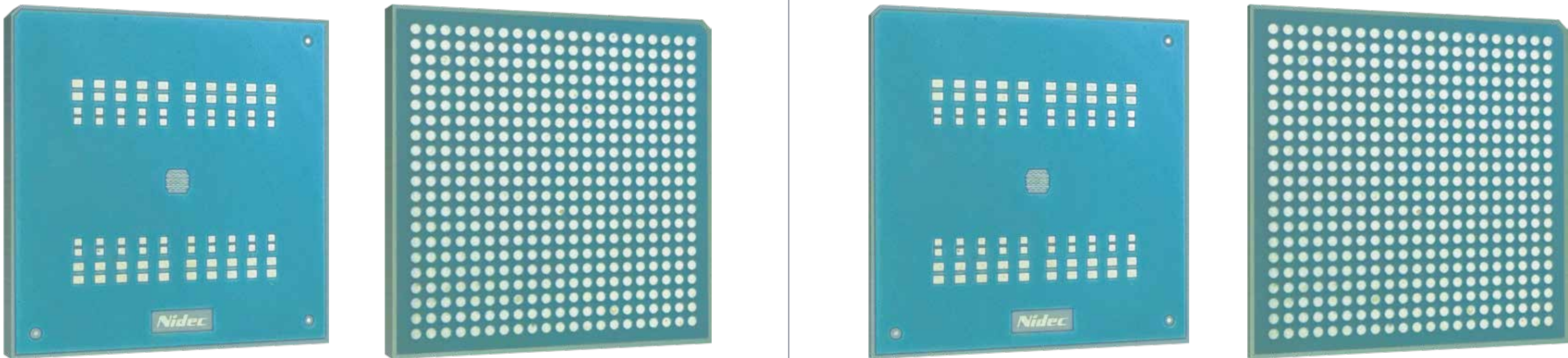


Sample		
O.D.	23mmSQ	←
Structure	2/2/2	←
Thickness	1mm	250um
Pad Pitch	120um	←
Pad DIA.	70um	←
L/S	17/20um	←

特徴 | Characteristics

- SAP工法による MLO基板の少量、試作レベルの数量でカスタム品製作が可能**
 Custom MLO substrates can be produced in small quantities at the prototype level using the SAP process.
- 薄物対応として全層SAP工法による製作が可能。**
 Thin substrates can be manufactured using the full-layer SAP process.
- 厚物から薄物までぜひ製品開発の一助にお役立てください**
 Please utilize our products—from thick to thin—to assist in your product development.

- カスタム設計歓迎 Custom design welcome
- 薄コア基板使用可能 (~40um) Thin core material (~40um)
- 挟ピッチ、小径ビア Small Pitch and Small Via Diameter

SAP Design Rule

	~2025	2026 1H~
Via DIA.	25 um	←
Min. Via Land DIA.	50 um	←
Min. L/S	20 / 25 um	15 / 15 um
Min. C4 Pad Pitch	75 um	65 um
Min. C4 Pad DIA.	55 um	50 um